

# Welcome to **iMAPS** New England May 2<sup>nd</sup>, 2017

## **iMAPS** Mission Statement

*iMAPS leads the Microelectronics Packaging, Interconnect and Assembly Community, providing means of communicating, educating and interacting at all levels.*



Welcome to the 44<sup>th</sup> Annual **iMAPS** New England Symposium and Expo! This event is our effort to support the mission of the International Microelectronics Assembly and Packaging Society. Through the dedicated efforts of our volunteer staff we have put together a program that we feel reflects the current interest of our members and the ever evolving microelectronics industry. This year's event features presentations in RF and Microwave Technologies and Thermal Management as well as Nano electronics and Optoelectronic, Medical Device Packaging and Printed Electronics.

With the growing interest in sensor technology and the advances in optoelectronics, MEMS devices and nanomaterials we are witnessing exciting times. The use of these technologies to improve our everyday life is evident every time we drive a car or use a cell phone. We are currently just touching the surface of additive technologies that allow the printing of electronics and eliminating circuit boards and traditional packages altogether. We must wonder, where will it lead us?

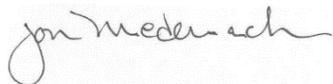
We have an outstanding technical program thanks to the efforts of our Technical Chairman, Parshant Kumar of Draper with the help of Dmitry Marchenko of BAE as well as a host of session chairs. Many thanks for their effort in putting together this fantastic program! I should mention this is the largest regional event within **iMAPS** and is entirely volunteer run.

Creativity is thinking about new things, innovation is doing new things. We hope that our efforts help to inspire creativity and innovation through education and networking with fellow members. Please take advantage of the technical offerings as well as the exposition to learn about new services, materials and equipment. This event would not be possible without the support of the exhibitors that represent all levels of the microelectronics supply chain. Please be sure to visit the exhibits and make a special effort to recognize our Gold and Silver Sponsors for their contribution to the Society.

The expo itself is an enormous undertaking and would not be possible without the efforts of our Executive Committee. Thanks to John B, Mike G, Harvey, Minh, Joe, Tom, Jeremy, Michael T, Dmitry, John R, Jim, Amaresh, Rozalia and a special thanks to Judi for hard work and creativity. We sincerely hope you enjoy the event.

We will have the luncheon and keynote speaker in the Exhibit Hall to promote networking with the exhibitors and fellow attendees. We will have refreshments and entertainment in the Exhibit Hall in the afternoon along with a chance to win some outstanding prizes supplied by our exhibitors and the Society. Be sure to attend for some fun and a chance to win!

Thank you for your attendance, Enjoy the day!

A handwritten signature in cursive script that reads "Jon Medernach".

Jon Medernach

**iMAPS** New England President